COMPLIANT HALOGEN

FREE



Vishay Semiconductors

Hyperfast Rectifier, 30 A FRED Pt®



PRIMARY CHARACTERISTICS								
I _{F(AV)}	30 A							
V_{R}	600 V							
V _F at I _F	1.34 V							
t _{rr} (typ.)	23 ns							
T _J max.	175 °C							
Package	2L TO-220AC							
Circuit configuration	Single							

FEATURES

- Reduced Q_{rr} and soft recovery
- 175 °C T_{.I} maximum
- For PFC CRM/CCM operation
- Low forward voltage drop
- Low leakage current
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

DESCRIPTION / APPLICATIONS

State of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC boost stage in the AC/DC section of SMPS, inverters or as freewheeling diodes.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS									
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS					
Peak repetitive reverse voltage	V_{RRM}		600	V					
Average rectified forward current	I _{F(AV)}	T _C = 103 °C	30	۸					
Non-repetitive peak surge current	I _{FSM}	T _J = 25 °C	200	Α					
Operating junction and storage temperatures	T _J , T _{Stg}		-65 to +175	°C					

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)										
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS				
Breakdown voltage, blocking voltage	V_{BR} , V_{R}	I _R = 100 μA	600	-	-	.,				
Forward voltage	V _F	I _F = 30 A	-	2.0	2.6	V				
		I _F = 30 A, T _J = 150 °C	-	1.34	1.75					
Reverse leakage current	I _R	$V_R = V_R$ rated	-	0.3	50					
		T _J = 150 °C, V _R = V _R rated	-	60	500	μΑ				
Junction capacitance	C _T	V _R = 600 V	-	33	-	pF				
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8.0	-	nΗ				



DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)										
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS			
Reverse recovery time		$I_F = 1 A, dI_F/dt = 50 A$	$/\mu s$, $V_R = 30 V$	-	28	35				
		$I_F = 1 \text{ A}, dI_F/dt = 100 \text{ A}$	-	23	30					
	t _{rr}	T _J = 25 °C		-	31	-	ns			
		T _J = 125 °C		-	77	-				
Dools recovery comment	I _{RRM}	T _J = 25 °C	I _F = 30 A	-	3.5	-	A nC			
Peak recovery current		T _J = 125 °C	$dI_F/dt = 200 \text{ A/}\mu\text{s}$ $V_R = 200 \text{ V}$	-	7.7	-				
Reverse recovery charge	Q _{rr}	T _J = 25 °C	VH - 200 V	-	65	-				
		T _J = 125 °C		-	345	ı	110			

THERMAL - MECHANICAL SPECIFICATIONS									
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS			
Maximum junction and storage temperature range	T _J , T _{Stg}		-65	-	175	°C			
Thermal resistance, junction to case per leg	R _{thJC}		-	0.7	1.1				
Thermal resistance, junction to ambient per leg	R _{thJA}	R _{thJA} Typical socket mount		-	70	°C/W			
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth, and greased	-	0.2	-				
Weight			-	2.0	-	g			
vveigni			-	0.07	-	OZ.			
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)			
Marking device		Case style 2L TO-220AC	30ETH06						

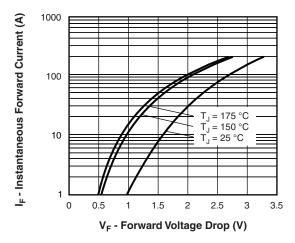


Fig. 1 - Typical Forward Voltage Drop Characteristics

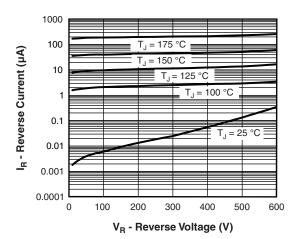


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

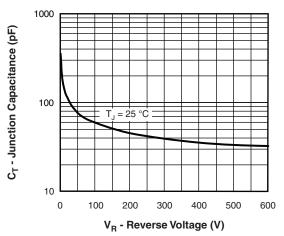


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

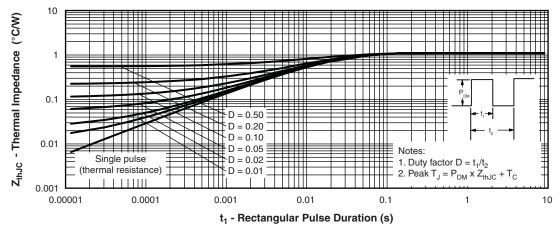


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

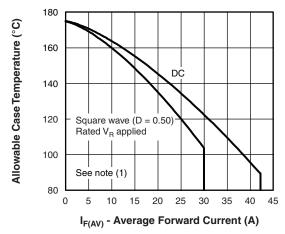


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

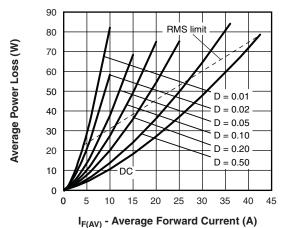


Fig. 6 - Forward Power Loss Characteristics

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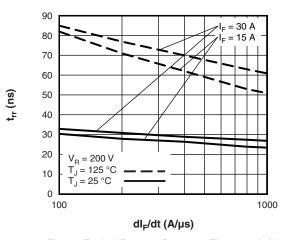


Fig. 7 - Typical Reverse Recovery Time vs. dI_{F}/dt

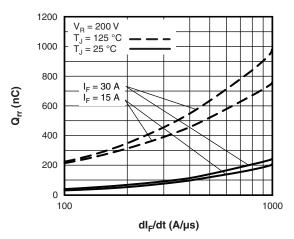
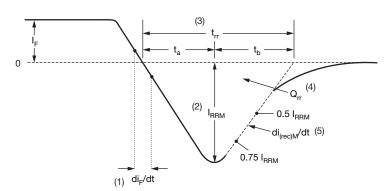


Fig. 8 - Typical Stored Charge vs. dl_F/dt

Note

 $\begin{array}{ll} \text{(1)} & \text{Formula used: } T_C = T_J - (\text{Pd} + \text{Pd}_{\text{REV}}) \times R_{\text{thJC}}; \\ \text{Pd} = & \text{forward power loss} = I_{\text{F(AV)}} \times V_{\text{FM}} \text{ at } (I_{\text{F(AV)}}/D) \text{ (see fig. 6)}; \\ \text{Pd}_{\text{REV}} = & \text{inverse power loss} = V_{\text{R1}} \times I_{\text{R}} \text{ (1 - D)}; I_{\text{R}} \text{ at } V_{\text{R1}} = \text{rated } V_{\text{R}} \\ \end{array}$



- (1) di_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) t_{rr} reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RRM} and 0.50 I_{RRM} extrapolated to zero current.
- (4) \mathbf{Q}_{rr} area under curve defined by \mathbf{t}_{rr} and \mathbf{I}_{RRM}

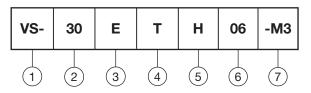
$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 9 - Reverse Recovery Waveform and Definitions

ORDERING INFORMATION TABLE

Device code



Vishay Semiconductors product

2 - Current rating (30 = 30 A)

3 - E = single

4 - Package:

T = 2L TO-220AC

5 - H = hyperfast recovery

6 - Voltage rating (06 = 600 V)

7 - Environmental digit:

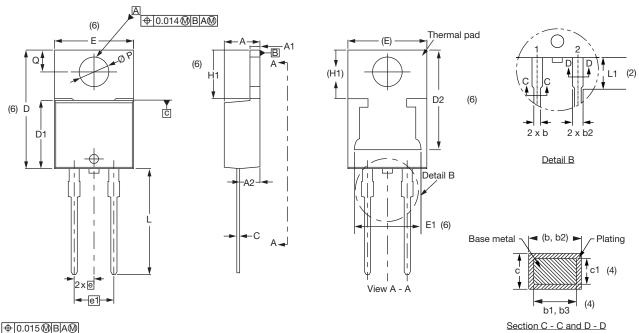
-M3 = halogen-free, RoHS-compliant, and termination lead (Pb)-free

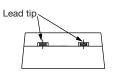
ORDERING INFORMATION (Example)									
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION						
VS-30ETH06-M3	50	1000	Antistatic plastic tube						

LINKS TO RELATED DOCUMENTS							
Dimensions	www.vishay.com/doc?96156						
Part marking information	www.vishay.com/doc?95391						
SPICE model	www.vishay.com/doc?95422						

2L TO-220AC

DIMENSIONS in millimeters and inches





Conforms to JEDEC® outline TO-220AC

SYMBOL	MILLIMETERS		ERS INCHES		NOTES	SYMBOL	MILLIN	IETERS	INC	HES	NOTES
STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES	STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.25	4.65	0.167	0.183		D2	11.68	13.30	0.460	0.524	6, 7
A1	1.14	1.40	0.045	0.055		E	10.11	10.51	0.398	0.414	3, 6
A2	2.50	2.92	0.098	0.115		E1	6.86	8.89	0.270	0.350	6
b	0.69	1.01	0.027	0.040		е	2.41	2.67	0.095	0.105	
b1	0.38	0.97	0.015	0.038	4	e1	4.88	5.28	0.192	0.208	
b2	1.20	1.73	0.047	0.068		H1	6.09	6.48	0.240	0.255	6
b3	1.14	1.73	0.045	0.068	4	L	13.52	14.02	0.532	0.552	
С	0.36	0.61	0.014	0.024		L1	3.32	3.82	0.131	0.150	2
c1	0.36	0.56	0.014	0.022	4	ØΡ	3.54	3.91	0.139	0.154	
D	14.85	15.35	0.585	0.604	3	Q	2.60	3.00	0.102	0.118	
D1	8.38	9.02	0.330	0.355							

Notes

- ⁽¹⁾ Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Dimension b1, b3, and c1 apply to base metal only
- Controlling dimensions: inches
- (6) Thermal pad contour optional within dimensions E, H1, D2, and E1
- (7) Outline conforms to JEDEC® TO-220, except D2



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